IN THE CLAIMS

Please amend the presently pending claims as follows:

1. (Previously Presented) Method for reshaping a set of conductive elements distributed on the bottom surface of an electronic module, said set of conductive elements forming means to transfer the module onto a motherboard and/or electromagnetic shielding means for the bottom surface of the module and/or electrical interconnection means with the motherboard,

wherein said method comprises a module stress reflow step, in a volume with walls of predetermined shapes, to enable stress release between at least some of the constituent elements of the module, such that the tops of the free ends of the set of conductive elements fit a predetermined two-dimensional or three-dimensional envelope.

2. (Previously Presented) Method according to claim 1, wherein the volume with walls of predetermined shapes is a volume wherein the first wall, intended to be in contact with the tops of the free ends of the set of conductive elements, is a plane wall,

the predetermined two-dimensional or three-dimensional envelope being a plane, said reshaping being restoring of the surface flatness.

3. (Previously Presented) Method according to claim 2, wherein the volume with walls of predetermined shapes is a volume wherein a second wall, intended to be in contact with the surface of the module opposite that whereon the conductive elements are distributed, is a plane wall.

4. (Previously Presented) Method according to claim 1, wherein the module stress reflow step comprises the following steps:

- positioning of the module on a plate;
- positioning of a back-plate on the plate, so as to trap and apply stress to the module in

the volume with walls of predetermined shapes formed between the plate and the back-plate;

- placing of the plate/module/back-plate superposition in a furnace, and heating according to a suitable temperature profile to enable stress release between at least some of the constituent elements of the module.

5. (Currently Amended) Method according to claim 4, wherein the heating step is followed by the following steps:

- cooling of the plate/module-back-plate superposition by cooling means;
- release of the module from the volume with walls of predetermined shapes.

6. (Previously Presented) Method according to claim 4, said electronic module comprising at least one substrate, wherein said temperature profile is defined so as to exceed the vitreous transition point of the substrate to modify its mechanical constants and enable it to be deformed.

7. (Previously Presented) Method according to claim 4, said electronic module comprising at least one substrate and at least one connector attached by at least one solder seam, wherein said temperature profile is defined so as to release the mechanical stress on the solder seams between said connectors and at least one organic substrate, when said substrate is of the connectorised type.

8. (Previously Presented) Method according to claim 3, wherein, during the module positioning step on the plate, the module is positioned in a suitable housing formed in the plate.

9. (Previously Presented) Method according to claim 3, wherein the back-plate positioning step on the plate comprises a back-plate tightening step against the plate, so as to optimise the application of stress to the module in the volume with walls of predetermined shapes formed between the plate and the back-plate.

10. (Previously Presented) Application of the method according to claim 1 to a radiocommunication module.

11. (Previously Presented) Application of the method according to claim 1, to a module comprising conductive elements belonging the group comprising: columns, beads, inserts and loops.

12. (Previously Presented) Application of the method according to claim 1 to a module comprising:

- a printed circuit board whereon components are mounted;
- an interposition structure, wherein:

a first surface supports a first set of conductive elements, so as to enable the transfer of said interposition structure, via its first surface, onto the bottom surface of said printed circuit board;

a second surface supports a second set of conductive elements, so as to enable the transfer of the module onto the motherboard, by transferring said interposition structure, via its second surface, onto the motherboard;

wherein said method enables the reshaping of the second set of conductive elements.

13. (Previously Presented) Application according to claim 12, wherein the first and second sets of conductive elements are combined, the elements supported by the first surface of the interposition structure being pass-through and projecting onto the second surface of the interposition structure,

and in that said method is used to reshape the free ends of the conductive elements projecting onto the second surface of the interposition structure.

14.(Previously Presented) Application according to claim 12, wherein the first and second sets of conductive elements are not combined, each of the elements of the first set being connected to a

first end of a conductive pass-through opening, a second end of each pass-through opening being connected to an element of the second set,

and in that said method is used to reshape the free ends of the conductive elements of the second set.

15. (Previously Presented) Device for reshaping a set of conductive elements distributed on the bottom surface of an electronic module, said set of conductive elements forming means to transfer the module onto a motherboard and/or electromagnetic shielding means for the bottom surface of the module and/or electrical interconnection means with the motherboard,

wherein said device comprises module stress reflow means, in a volume with walls of predetermined shapes, to enable stress release between at least some of the constituent elements of the module, such that the tops of the free ends of the set of conductive elements fit a predetermined two-dimensional or three-dimensional envelope.

16. (Previously Presented) Device according to claim 15, wherein the volume with walls of predetermined shapes is a volume wherein the first wall, intended to be in contact with the tops of the free ends of the set of conductive elements, is a plane wall,

the predetermined two-dimensional or three-dimensional envelope being a plane, said reshaping being restoring of the surface flatness.

17. (Previously Presented) Device according to claim 16, wherein the volume with walls of predetermined shapes is a volume wherein a second wall, intended to be in contact with the surface of the module opposite that whereon the conductive elements are distributed, is a plane wall.

18. (Previously Presented) Device according to claim 15, wherein the module stress reflow means comprise:

- a plate whereon the module is positioned;

- a back-plate, intended to be positioned on the plate, so as to trap and apply stress to the module in the volume with walls of predetermined shapes formed between the plate and the back-plate;

- a furnace in which the plate/module/back-plate superposition is placed, and used to heat the superposition according to a suitable temperature profile to enable stress release between at least some of the constituent elements of the module.

19. (Previously Presented) Device according to claim 18, wherein the module stress reflow means also comprise:

- plate/module-back-plate superposition cooling means;
- means to release the module from the volume with walls of predetermined shapes.

20. (Previously Presented) Device according to claim 18, said electronic module comprising at least one substrate, wherein it comprises temperature profile application means making it possible to exceed the vitreous transition point of the substrate to modify its mechanical constants and enable it to be deformed.

21. (Previously Presented) Device according to claim 18, said electronic module comprising at least one substrate and at least one connector attached by at least one solder seam, wherein it comprises temperature profile application means making it possible to release the mechanical stress on the solder seams between said connectors and at least one organic substrate.

22. (Previously Presented) Device according to claim 18, wherein the plate comprise a housing wherein the shape is suitable to receive the module.

23. (Previously Presented) Device according to claim 18 wherein the back-plate positioning means on the plate comprise means to tighten the back-plate against the plate, making it possible to optimise the application of stress to the module in the volume with walls of predetermined

shapes formed between the plate and the back-plate.

24. (Previously Presented) Production method for electronic modules of the type each comprising a set of conductive elements distributed on the bottom surface of the module, said set of conductive elements forming means to transfer the module onto a motherboard and/or electromagnetic shielding means for the bottom surface of the module and/or electrical interconnection means with the motherboard,

wherein said production method comprises a step implementing the above-mentioned method for reshaping a set of conductive elements distributed on the bottom surface of an electronic module.

25. (Previously Presented) Method according to claim 24, wherein the reshaping method implementation step is performed systematically, for all the modules manufactured.

26. (Previously Presented) Method according to claim 24, wherein the method comprises a detection step of manufactured modules, referred to as defective modules, showing a shape defect, greater than a predetermined threshold, on the tops of the free ends of the conductive elements with respect to a predetermined two-dimensional or three-dimensional envelope

and wherein the reshaping method implementation step is only performed for said defective modules.